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April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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**4M-BIT CMOS STATIC RAM
256K-WORD BY 16-BIT
EXTENDED TEMPERATURE OPERATION**

Description

The μ PD444012A-X is a high speed, low power, 4,194,304 bits (262,144 words by 16 bits) CMOS static RAM.

The μ PD444012A-X has two chip enable pins (/CE1, CE2) to extend the capacity.

The μ PD444012A-X is packed in 48-pin PLASTIC TSOP (I) (Normal bent).

Features

- 262,144 words by 16 bits organization
- Fast access time: 50, 55, 70, 85, 100, 120 ns (MAX.)
- Byte data control: /LB (I/O1 - I/O8), /UB (I/O9 - I/O16)
- Low voltage operation
(B version: $V_{CC} = 2.7$ to 3.6 V, C version: $V_{CC} = 2.2$ to 3.6 V)
- Low V_{CC} data retention: 1.0 V (MIN.)
- Operating ambient temperature: $T_A = -25$ to $+85^\circ\text{C}$
- Output Enable input for easy application
- Two Chip Enable inputs: /CE1, CE2

Part number	Access time ns (MAX.)	Operating supply Voltage V	Operating ambient temperature $^\circ\text{C}$	Supply current		
				At operating mA (MAX.)	At standby μA (MAX.)	At data retention μA (MAX.)
μ PD444012A-BxxxX	50 ^{Note 1} , 55, 70, 85, 100	2.7 to 3.6	-25 to +85	40 ^{Note 2}	7	3
				45 ^{Note 3}		
				50 ^{Note 4}		
μ PD444012A-CxxxX	70, 85, 100, 120	2.2 to 3.6		40		

Notes 1. $V_{CC} \geq 3.0$ V

2. Cycle time ≥ 70 ns
3. Cycle time = 55 ns
4. Cycle time = 50 ns

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Ordering Information

Part number	Package	Access time ns (MAX.)	Operating supply voltage V	Operating temperature °C	Remark
μPD444012AGY-B55X-MJH	48-pin PLASTIC TSOP (I) (12×18) (Normal bent)	55, 50 ^{Note}	2.7 to 3.6	-25 to +85	B version
μPD444012AGY-B70X-MJH		70			
μPD444012AGY-B85X-MJH		85			
μPD444012AGY-B10X-MJH		100			
μPD444012AGY-C70X-MJH		70	2.2 to 3.6		C version
μPD444012AGY-C85X-MJH		85			
μPD444012AGY-C10X-MJH		100			
μPD444012AGY-C12X-MJH		120			
μPD444012AGY-B55X-MJH-A		55, 50 ^{Note}	2.7 to 3.6	-25 to +85	B version
μPD444012AGY-B70X-MJH-A		70			
μPD444012AGY-B85X-MJH-A		85			
μPD444012AGY-B10X-MJH-A		100			
μPD444012AGY-C70X-MJH-A		70	2.2 to 3.6		C version
μPD444012AGY-C85X-MJH-A		85			
μPD444012AGY-C10X-MJH-A		100			
μPD444012AGY-C12X-MJH-A		120			

Note V_{cc} ≥ 3.0 V

Remark Products with -A at the end of the part number are lead-free products.

Pin Configuration (Marking Side)

/xxx indicates active low signal.

48-pin PLASTIC TSOP (I) (12×18) (Normal bent)

[μPD444012AGY-BxxX-MJH]

[μPD444012AGY-CxxX-MJH]

[μPD444012AGY-BxxX-MJH-A]

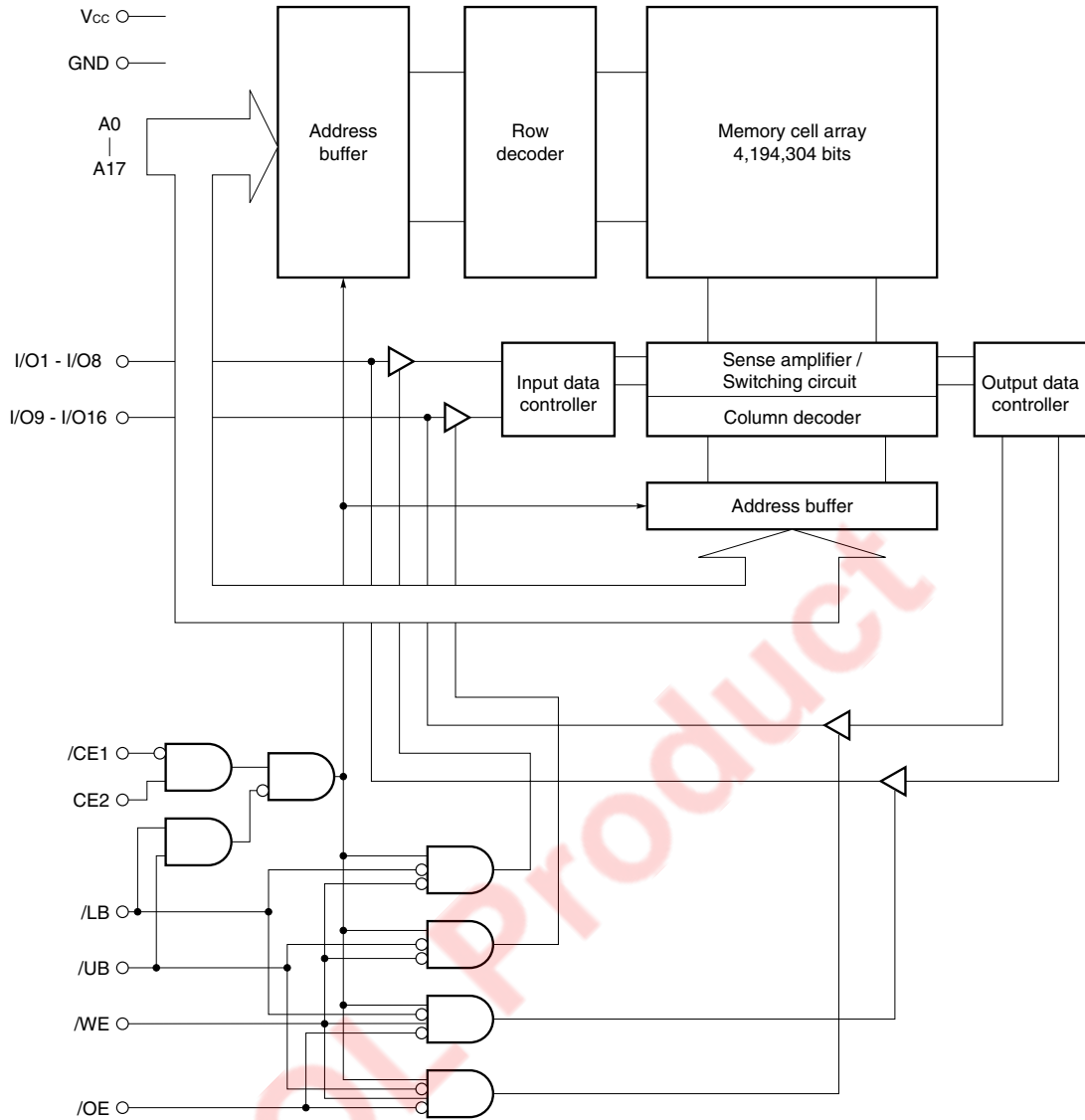
[μPD444012AGY-CxxX-MJH-A]



- A0 - A17 : Address inputs
- I/O1 - I/O16 : Data inputs / outputs
- /CE1, CE2 : Chip Enable 1, 2
- /WE : Write Enable
- /OE : Output Enable
- /LB, /UB : Byte data select
- Vcc : Power supply
- GND : Ground
- NC : No Connection

Remark Refer to **Package Drawing** for the 1-pin index mark.

Block Diagram



Truth Table

/CE1	CE2	/OE	/WE	/LB	/UB	Mode	I/O		Supply current	
							I/O1 - I/O8	I/O9 - I/O16		
H	x	x	x	x	x	Not selected	High impedance	High impedance	I _{SB}	
x	L	x	x	x	x		High impedance	High impedance		
L	H	H	H	x	x	Output disable	High impedance	High impedance	I _{CCA}	
		L	H	L	L	Word read	D _{OUT}	D _{OUT}		
				L	H	Lower byte read	D _{OUT}	High impedance		
				H	L	Upper byte read	High impedance	D _{OUT}		
		x	L	L	L	L	Word write	D _{IN}		D _{IN}
					L	H	Lower byte write	D _{IN}		High impedance
H	L				Upper byte write	High impedance	D _{IN}			
x	x	x	x	H	H	Not selected	High impedance	High impedance	I _{SB}	

Remark x : V_{IH} or V_{IL}

Electrical Specifications

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Supply voltage	V _{CC}		-0.5 ^{Note} to +4.0	V
Input / Output voltage	V _T		-0.5 ^{Note} to V _{CC} + 0.4 (4.0 V MAX.)	V
Operating ambient temperature	T _A		-25 to +85	°C
Storage temperature	T _{stg}		-55 to +125	°C

Note -3.0 V (MIN.) (Pulse width : 30 ns)

Caution Exposing the device to stress above those listed in Absolute Maximum Rating could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	μPD444012A-BxxX		μPD444012A-CxxX		Unit
			MIN.	MAX.	MIN.	MAX.	
Supply voltage	V _{CC}		2.7	3.6	2.2	3.6	V
High level input voltage	V _{IH}	2.7 V ≤ V _{CC} ≤ 3.6 V	2.4	V _{CC} +0.4	2.4	V _{CC} +0.4	V
		2.2 V ≤ V _{CC} < 2.7 V	-	-	2.0	V _{CC} +0.3	
Low level input voltage	V _{IL}		-0.3 ^{Note}	+0.5	-0.3 ^{Note}	+0.3	V
Operating ambient temperature	T _A		-25	+85	-25	+85	°C

Note -1.5 V (MIN.) (Pulse width: 30 ns)

Capacitance (T_A = 25°C, f = 1 MHz)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C _{IN}	V _{IN} = 0 V			8	pF
Input / Output capacitance	C _{I/O}	V _{I/O} = 0 V			10	pF

Remarks 1. V_{IN} : Input voltage

V_{I/O} : Input / Output voltage

2. These parameters are not 100% tested.

DC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)(1/2)

Parameter	Symbol	Test condition	V _{CC} ≥ 2.7 V			Unit
			μPD444012A-BxxX			
			MIN.	TYP.	MAX.	
Input leakage current	I _{LI}	V _{IN} = 0 V to V _{CC}	-1.0		+1.0	μA
I/O leakage current	I _{LO}	V _{I/O} = 0 V to V _{CC} , /CE1 = V _{IH} or CE2 = V _{IL} or /WE = V _{IL} or /OE = V _{IH}	-1.0		+1.0	μA
Operating supply current	I _{CCA1}	/CE1 = V _{IL} , CE2 = V _{IH} , Minimum cycle time, I _{I/O} = 0 mA	Cycle time = 50 ns	-	50	mA
			Cycle time = 55 ns	-	45	
			Cycle time ≥ 70 ns	-	40	
	I _{CCA2}	/CE1 = V _{IL} , CE2 = V _{IH} , I _{I/O} = 0 mA, Cycle time = ∞		-	4	
I _{CCA3}	/CE1 ≤ 0.2 V, CE2 ≥ V _{CC} - 0.2 V, Cycle time = 1 μs, I _{I/O} = 0 mA, V _{IL} ≤ 0.2 V, V _{IH} ≥ V _{CC} - 0.2 V		-	6		
Standby supply current	I _{SB}	/CE1 = V _{IH} or CE2 = V _{IL} or /LB = /UB = V _{IH}		-	0.6	mA
	I _{SB1}	/CE1 ≥ V _{CC} - 0.2 V, CE2 ≥ V _{CC} - 0.2 V		0.5	7	
	I _{SB2}	CE2 ≤ 0.2 V		0.5	7	
	I _{SB3}	/LB = /UB ≥ V _{CC} - 0.2 V, /CE1 ≤ 0.2 V, CE2 ≥ V _{CC} - 0.2 V		0.5	7	
High level output voltage	V _{OH}	I _{OH} = -0.5 mA	2.4			V
Low level output voltage	V _{OL}	I _{OL} = 1.0 mA			0.4	V

Remarks 1. V_{IN} : Input voltage

V_{I/O} : Input / Output voltage

2. These DC characteristics are in common regardless of product specification.

DC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)(2/2)

Parameter	Symbol	Test condition	V _{CC} ≥ 2.2 V			Unit
			μPD444012A-CxxX			
			MIN.	TYP.	MAX.	
Input leakage current	I _{LI}	V _{IN} = 0 V to V _{CC}	-1.0		+1.0	μA
I/O leakage current	I _{LO}	V _{I/O} = 0 V to V _{CC} , /CE1 = V _{IH} or CE2 = V _{IL} or /WE = V _{IL} or /OE = V _{IH}	-1.0		+1.0	μA
Operating supply current	I _{CCA1}	/CE1 = V _{IL} , CE2 = V _{IH} , Minimum cycle time, I _{I/O} = 0 mA	V _{CC} ≤ 2.7 V	-	40	mA
				-	25	
	I _{CCA2}	/CE1 = V _{IL} , CE2 = V _{IH} , I _{I/O} = 0 mA, Cycle time = ∞	V _{CC} ≤ 2.7 V	-	4	
				-	2	
I _{CCA3}	/CE1 ≤ 0.2 V, CE2 ≥ V _{CC} - 0.2 V, Cycle time = 1 μs, I _{I/O} = 0 mA, V _{IL} ≤ 0.2 V, V _{IH} ≥ V _{CC} - 0.2 V	V _{CC} ≤ 2.7 V	-	6		
			-	5		
Standby supply current	I _{SB}	/CE1 = V _{IH} or CE2 = V _{IL} or /LB = /UB = V _{IH}	V _{CC} ≤ 2.7 V	-	0.6	mA
				-	0.6	
	I _{SB1}	/CE1 ≥ V _{CC} - 0.2 V, CE2 ≥ V _{CC} - 0.2 V	V _{CC} ≤ 2.7 V	0.5	7	μA
				0.4	6	
	I _{SB2}	CE2 ≤ 0.2 V	V _{CC} ≤ 2.7 V	0.5	7	
			0.4	6		
I _{SB3}	/LB = /UB ≥ V _{CC} - 0.2 V, /CE1 ≤ 0.2 V, CE2 ≥ V _{CC} - 0.2 V	V _{CC} ≤ 2.7 V	0.5	7		
			0.4	6		
High level output voltage	V _{OH}	I _{OH} = -0.5 mA		2.4		V
			V _{CC} ≤ 2.7 V	1.8		
Low level output voltage	V _{OL}	I _{OL} = 1.0 mA			0.4	V

Remarks 1. V_{IN} : Input voltage

V_{I/O} : Input / Output voltage

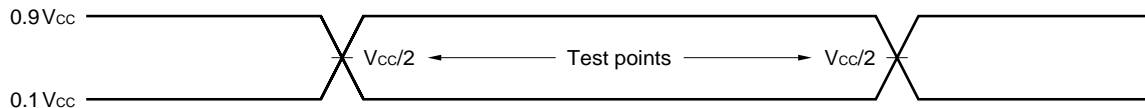
2. These DC characteristics are in common regardless of product classification.

AC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)

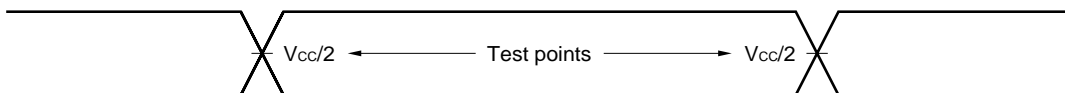
AC Test Conditions

[μ PD444012A-B55X, μ PD444012A-B70X, μ PD444012A-B85X, μ PD444012A-B10X]

Input Waveform (Rise and Fall Time \leq 5 ns)



Output Waveform

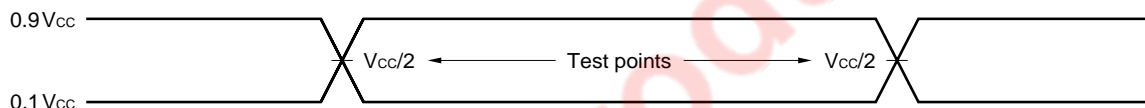


Output Load

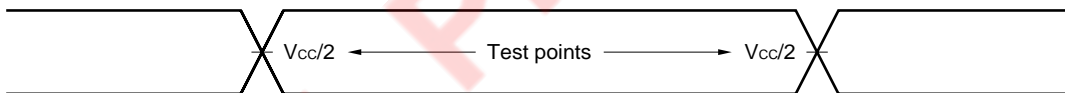
1TTL + 50 pF

[μ PD444012A-C70X, μ PD444012A-C85X, μ PD444012A-C10X, μ PD444012A-C12X]

Input Waveform (Rise and Fall Time \leq 5 ns)



Output Waveform



Output Load

1TTL + 30 pF

Read Cycle (1/2) (B version)

Parameter	Symbol	V _{CC} ≥ 3.0 V		V _{CC} ≥ 2.7 V								Unit	Condition
		μPD444012A		μPD444012A		μPD444012A		μPD444012A		μPD444012A			
		-B55X		-B55X		-B70X		-B85X		-B10X			
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read cycle time	t _{RC}	50		55		70		85		100		ns	
Address access time	t _{AA}		50		55		70		85		100	ns	Note 1
/CE1 access time	t _{CO1}		50		55		70		85		100	ns	
CE2 access time	t _{CO2}		50		55		70		85		100	ns	
/OE to output valid	t _{OE}		30		30		35		40		50	ns	
/LB, /UB to output valid	t _{BA}		50		55		70		85		100	ns	
Output hold from address change	t _{OH}	10		10		10		10		10		ns	
/CE1 to output in low impedance	t _{LZ1}	10		10		10		10		10		ns	Note 2
CE2 to output in low impedance	t _{LZ2}	10		10		10		10		10		ns	
/OE to output in low impedance	t _{OLZ}	0		0		0		0		0		ns	
/LB, /UB to output in low impedance	t _{BLZ}	10		10		10		10		10		ns	
/CE1 to output in high impedance	t _{HZ1}		20		20		25		30		35	ns	
CE2 to output in high impedance	t _{HZ2}		20		20		25		30		35	ns	
/OE to output in high impedance	t _{OHZ}		20		20		25		30		35	ns	
/LB, /UB to output in high impedance	t _{BHZ}		20		20		25		30		35	ns	

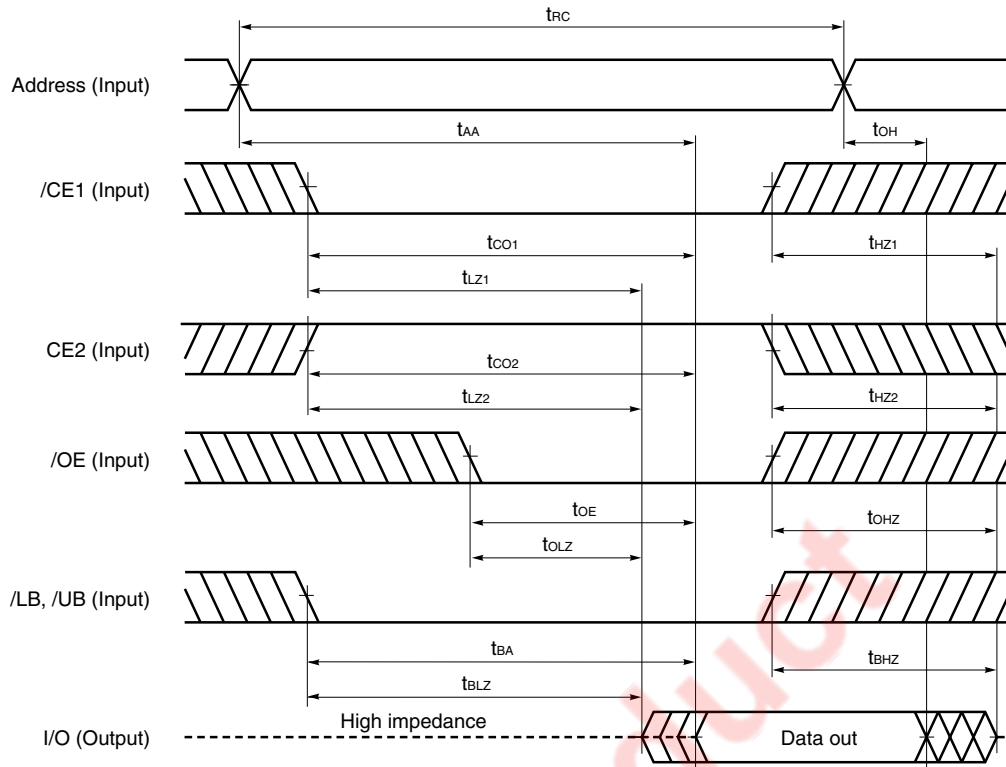
- Notes 1. The output load is 1TTL + 50 pF.
 2. The output load is 1TTL + 5 pF.

Read Cycle (2/2) (C version)

Parameter	Symbol	V _{CC} ≥ 2.2 V								Unit	Condition
		μPD444012A		μPD444012A		μPD444012A		μPD444012A			
		-C70X		-C85X		-C10X		-C12X			
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read cycle time	t _{RC}	70		85		100		120		ns	
Address access time	t _{AA}		70		85		100		120	ns	Note 1
/CE1 access time	t _{CO1}		70		85		100		120	ns	
CE2 access time	t _{CO2}		70		85		100		120	ns	
/OE to output valid	t _{OE}		35		40		50		60	ns	
/LB, /UB to output valid	t _{BA}		70		85		100		120	ns	
Output hold from address change	t _{OH}	10		10		10		10		ns	
/CE1 to output in low impedance	t _{LZ1}	10		10		10		10		ns	Note 2
CE2 to output in low impedance	t _{LZ2}	10		10		10		10		ns	
/OE to output in low impedance	t _{OLZ}	0		0		0		0		ns	
/LB, /UB to output in low impedance	t _{BLZ}	10		10		10		10		ns	
/CE1 to output in high impedance	t _{HZ1}		25		30		35		40	ns	
CE2 to output in high impedance	t _{HZ2}		25		30		35		40	ns	
/OE to output in high impedance	t _{OHZ}		25		30		35		40	ns	
/LB, /UB to output in high impedance	t _{BHZ}		25		30		35		40	ns	

- Notes 1. The output load is 1TTL + 30 pF.
 2. The output load is 1TTL + 5 pF.

Read Cycle Timing Chart



Remark In read cycle, /WE should be fixed to high level.

Write Cycle (1/2) (B version)

Parameter	Symbol	V _{CC} ≥ 3.0 V		V _{CC} ≥ 2.7 V								Unit	Condition
		μPD444012A		μPD444012A		μPD444012A		μPD444012A		μPD444012A			
		-B55X		-B55X		-B70X		-B85X		-B10X			
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Write cycle time	t _{wc}	50		55		70		85		100		ns	
/CE1 to end of write	t _{cw1}	45		50		55		70		80		ns	
CE2 to end of write	t _{cw2}	45		50		55		70		80		ns	
/LB, /UB to end of write	t _{bw}	45		50		55		70		80		ns	
Address valid to end of write	t _{aw}	45		50		55		70		80		ns	
Address setup time	t _{as}	0		0		0		0		0		ns	
Write pulse width	t _{wp}	40		45		50		55		60		ns	
Write recovery time	t _{wr}	0		0		0		0		0		ns	
Data valid to end of write	t _{dw}	25		25		30		35		40		ns	
Data hold time	t _{dh}	0		0		0		0		0		ns	
/WE to output in high impedance	t _{whz}		20		20		25		30		35	ns	Note
Output active from end of write	t _{ow}	5		5		5		5		5		ns	

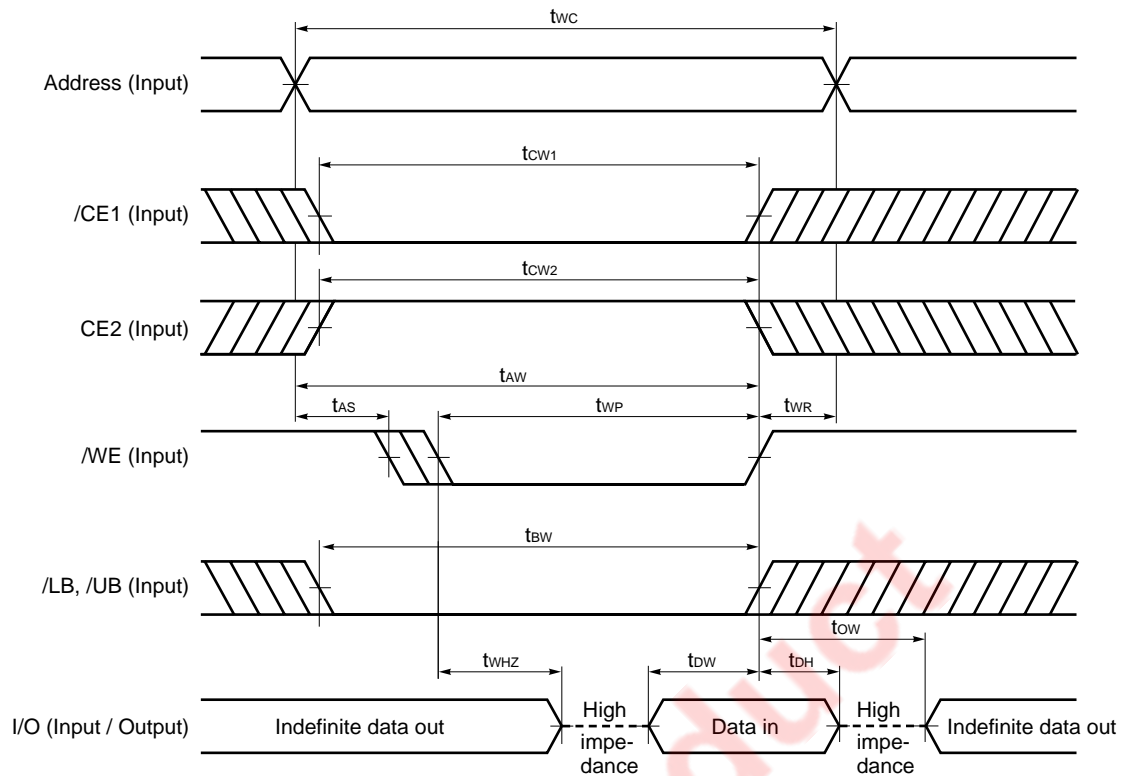
Note The output load is 1TTL + 5 pF.

Write Cycle (2/2) (C version)

Parameter	Symbol	V _{CC} ≥ 2.2 V								Unit	Condition
		μPD444012A		μPD444012A		μPD444012A		μPD444012A			
		-C70X		-C85X		-C10X		-C12X			
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Write cycle time	t _{wc}	70		85		100		120		ns	
/CE1 to end of write	t _{cw1}	55		70		80		100		ns	
CE2 to end of write	t _{cw2}	55		70		80		100		ns	
/LB, /UB to end of write	t _{bw}	55		70		80		100		ns	
Address valid to end of write	t _{aw}	55		70		80		100		ns	
Address setup time	t _{as}	0		0		0		0		ns	
Write pulse width	t _{wp}	50		55		60		85		ns	
Write recovery time	t _{wr}	0		0		0		0		ns	
Data valid to end of write	t _{dw}	30		35		40		60		ns	
Data hold time	t _{dh}	0		0		0		0		ns	
/WE to output in high impedance	t _{whz}		25		30		35		40	ns	Note
Output active from end of write	t _{ow}	5		5		5		5		ns	

Note The output load is 1TTL + 5 pF.

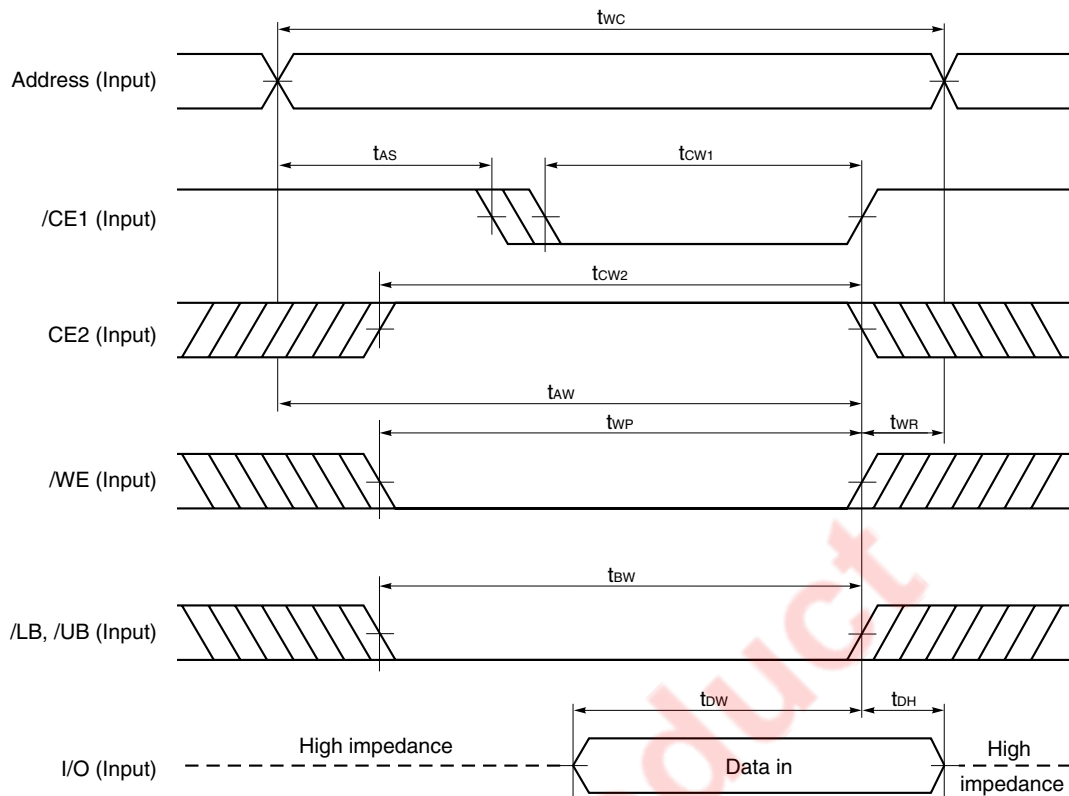
Write Cycle Timing Chart 1 (/WE Controlled)



- Cautions**
1. During address transition, at least one of pins /CE1, CE2, /WE should be inactivated.
 2. Do not input data to the I/O pins while they are in the output state.

- Remarks**
1. Write operation is done during the overlap time of a low level /CE1, /WE, /LB and/or /UB, and a high level CE2.
 2. If /CE1 changes to low level at the same time or after the change of /WE to low level, or if CE2 changes to high level at the same time or after the change of /WE to low level, the I/O pins will remain high impedance state.
 3. When /WE is at low level, the I/O pins are always high impedance. When /WE is at high level, read operation is executed. Therefore /OE should be at high level to make the I/O pins high impedance.

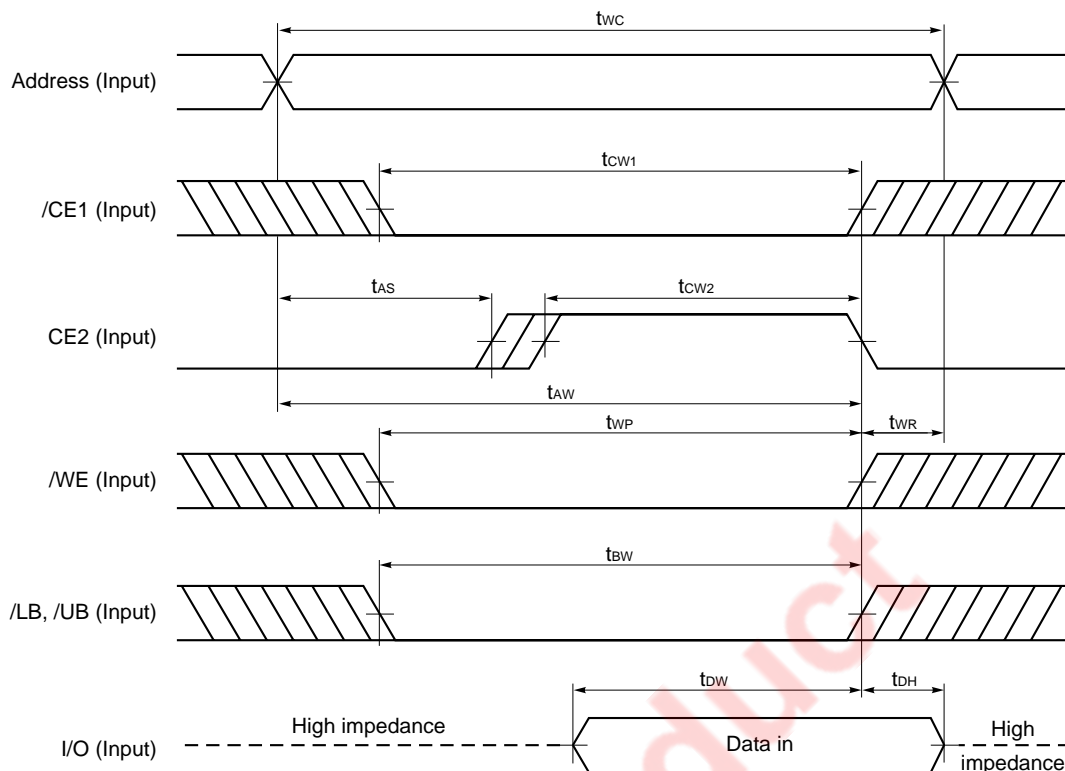
Write Cycle Timing Chart 2 (/CE1 Controlled)



- Cautions**
1. During address transition, at least one of pins /CE1, CE2, /WE should be inactivated.
 2. Do not input data to the I/O pins while they are in the output state.

Remark Write operation is done during the overlap time of a low level /CE1, /WE, /LB and/or /UB, and a high level CE2.

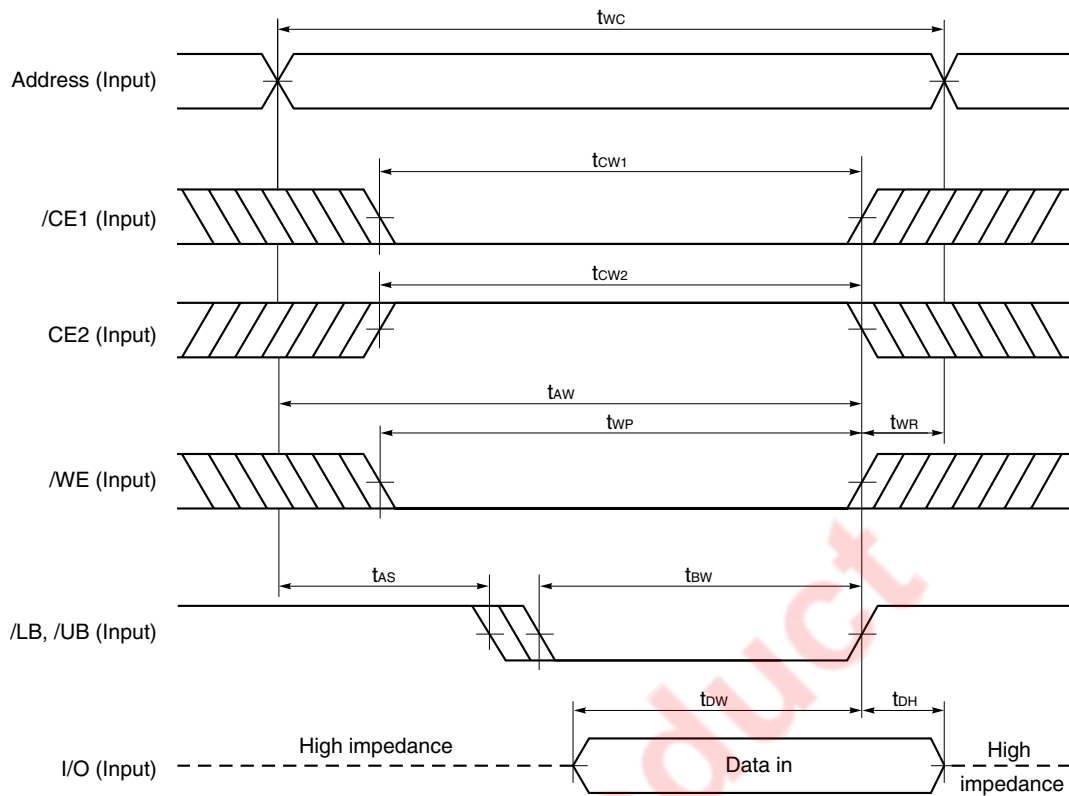
Write Cycle Timing Chart 3 (CE2 Controlled)



- Cautions**
1. During address transition, at least one of pins /CE1, CE2, /WE should be inactivated.
 2. Do not input data to the I/O pins while they are in the output state.

Remark Write operation is done during the overlap time of a low level /CE1, /WE, /LB and/or /UB, and a high level CE2.

Write Cycle Timing Chart 4 (/LB, /UB Controlled)



- Cautions**
1. During address transition, at least one of pins /CE1, CE2, /WE should be inactivated.
 2. Do not input data to the I/O pins while they are in the output state.

Remark Write operation is done during the overlap time of a low level /CE1, /WE, /LB and/or /UB, and a high level CE2.

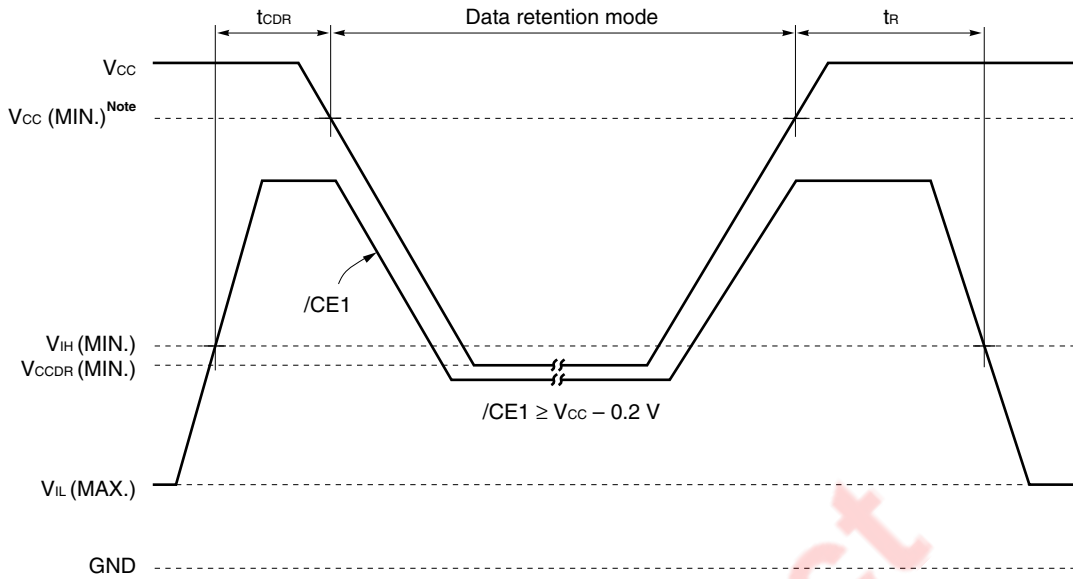
Low V_{CC} Data Retention Characteristics (T_A = -25 to +85°C)

Parameter	Symbol	Test Condition	V _{CC} ≥ 2.7 V			V _{CC} ≥ 2.2 V			Unit
			μPD444012A -BxxX			μPD444012A -CxxX			
			MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Data retention supply voltage	V _{CCDR1}	/CE1 ≥ V _{CC} - 0.2 V, CE2 ≥ V _{CC} - 0.2 V	1.0		3.6	1.0		3.6	V
	V _{CCDR2}	CE2 ≤ 0.2 V	1.0		3.6	1.0		3.6	
	V _{CCDR3}	/LB = /UB ≥ V _{CC} - 0.2 V, /CE1 ≤ 0.2 V, CE2 ≥ V _{CC} - 0.2 V	1.0		3.6	1.0		3.6	
Data retention supply current	I _{CCDR1}	V _{CC} = 1.5 V, /CE1 ≥ V _{CC} - 0.2 V, CE2 ≥ V _{CC} - 0.2 V		0.3	3.0		0.3	3.0	μA
	I _{CCDR2}	V _{CC} = 1.5 V, CE2 ≤ 0.2 V		0.3	3.0		0.3	3.0	
	I _{CCDR3}	V _{CC} = 1.5 V, /LB = /UB ≥ V _{CC} - 0.2 V, /CE1 ≤ 0.2 V, CE2 ≥ V _{CC} - 0.2 V		0.3	3.0		0.3	3.0	
Chip deselection to data retention mode	t _{CDR}		0			0			ns
Operation recovery time	t _r		t _{rc} ^{Note}			t _{rc} ^{Note}			ns

Note t_{rc} : Read cycle time

Data Retention Timing Chart

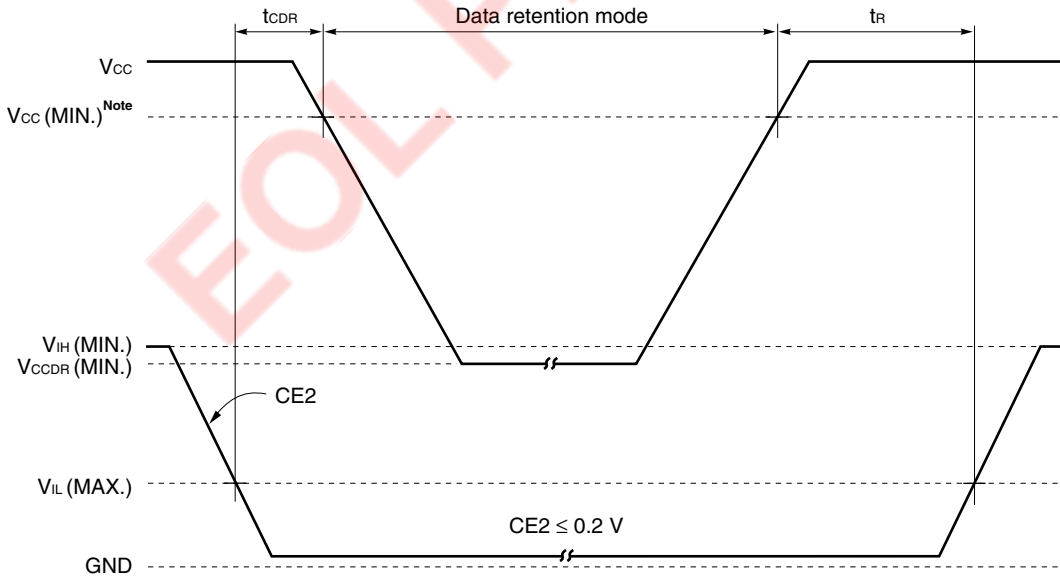
(1) /CE1 Controlled



Note B version : 2.7 V, C version : 2.2 V

Remark On the data retention mode by controlling $\overline{CE1}$, the input level of CE2 must be $\geq V_{CC} - 0.2 V$ or $\leq 0.2 V$. The other pins (Address, I/O, \overline{WE} , \overline{OE} , \overline{LB} , \overline{UB}) can be in high impedance state.

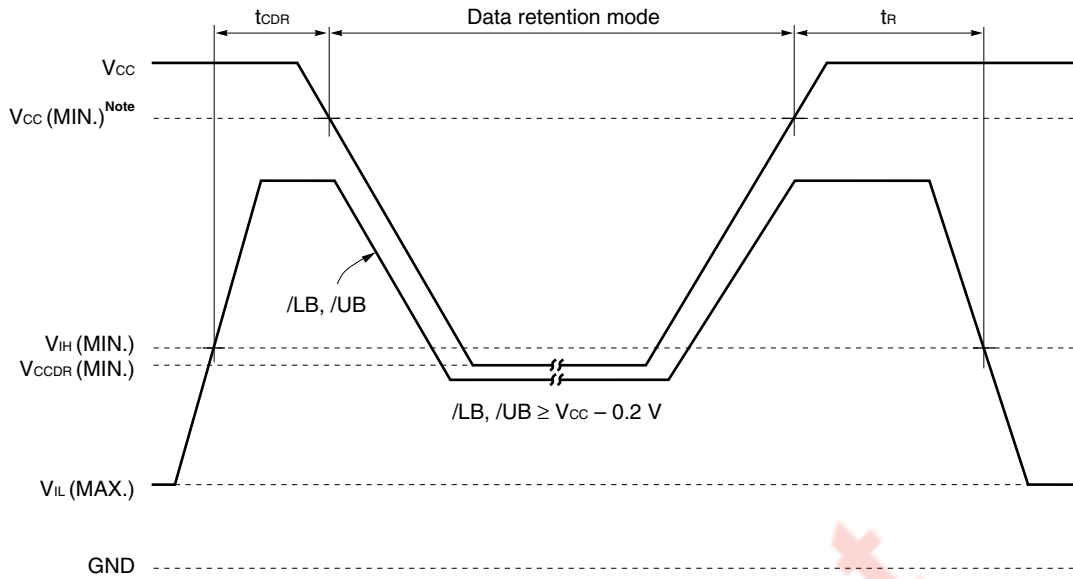
(2) CE2 Controlled



Note B version : 2.7 V, C version : 2.2 V

Remark On the data retention mode by controlling $CE2$, The other pins ($\overline{CE1}$, Address, I/O, \overline{WE} , \overline{OE} , \overline{LB} , \overline{UB}) can be in high impedance state.

(3) /LB, /UB Controlled



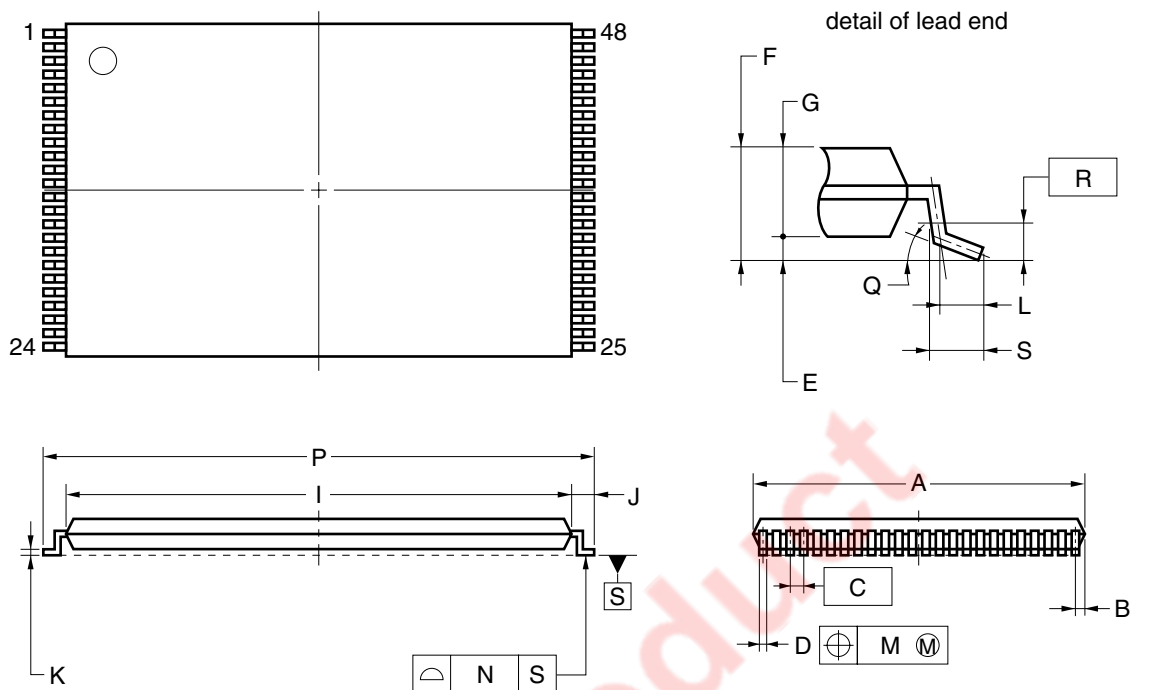
Note B version : 2.7 V, C version : 2.2 V

Remark On the data retention mode by controlling /LB and /UB, the input level of /CE1 and CE2 must be $\geq V_{CC} - 0.2 V$ or $\leq 0.2 V$. The other pins (Address, I/O, /WE, /OE) can be in high impedance state.

EOL Product

Package Drawing

48-PIN PLASTIC TSOP(I) (12x18)



NOTES

1. Each lead centerline is located within 0.10 mm of its true position (T.P.) at maximum material condition.
2. "A" excludes mold flash. (Includes mold flash : 12.4 mm MAX.)

ITEM	MILLIMETERS
A	12.0±0.1
B	0.45 MAX.
C	0.5 (T.P.)
D	0.22±0.05
E	0.1±0.05
F	1.2 MAX.
G	1.0±0.05
I	16.4±0.1
J	0.8±0.2
K	0.145±0.05
L	0.5
M	0.10
N	0.10
P	18.0±0.2
Q	3° ^{+5°} -3°
R	0.25
S	0.60±0.15

S48GY-50-MJH1-1

Recommended Soldering Conditions

Please consult with our sales offices for soldering conditions of the μ PD444012A-X.

Types of Surface Mount Device

μ PD444012AGY-BxxX-MJH : 48-pin PLASTIC TSOP (I) (12×18) (Normal bent)

μ PD444012AGY-CxxX-MJH : 48-pin PLASTIC TSOP (I) (12×18) (Normal bent)

μ PD444012AGY-BxxX-MJH-A : 48-pin PLASTIC TSOP (I) (12×18) (Normal bent)

μ PD444012AGY-CxxX-MJH-A : 48-pin PLASTIC TSOP (I) (12×18) (Normal bent)

<R> Quality Grade

- A quality grade of the products is "Standard".
- Anti-radioactive design is not implemented in the products.
- Semiconductor devices have the possibility of unexpected defects by affection of cosmic ray that reach to the ground and so forth.

EOL Product

Revision History

Edition/ Date	Page		Type of revision	Location	Description (Previous edition → This edition)
	This edition	Previous edition			
7th edition/ Sep. 2006	p.20	p.20	Addition	Quality Grade	Section of Quality Grade has been added.

EOL Product

[MEMO]

EOL Product

NOTES FOR CMOS DEVICES

① VOLTAGE APPLICATION WAVEFORM AT INPUT PIN

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (MAX) and V_{IH} (MIN) due to noise, etc., the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (MAX) and V_{IH} (MIN).

② HANDLING OF UNUSED INPUT PINS

Unconnected CMOS device inputs can be cause of malfunction. If an input pin is unconnected, it is possible that an internal input level may be generated due to noise, etc., causing malfunction. CMOS devices behave differently than Bipolar or NMOS devices. Input levels of CMOS devices must be fixed high or low by using pull-up or pull-down circuitry. Each unused pin should be connected to V_{DD} or GND via a resistor if there is a possibility that it will be an output pin. All handling related to unused pins must be judged separately for each device and according to related specifications governing the device.

③ PRECAUTION AGAINST ESD

A strong electric field, when exposed to a MOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it when it has occurred. Environmental control must be adequate. When it is dry, a humidifier should be used. It is recommended to avoid using insulators that easily build up static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors should be grounded. The operator should be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with mounted semiconductor devices.

④ STATUS BEFORE INITIALIZATION

Power-on does not necessarily define the initial status of a MOS device. Immediately after the power source is turned ON, devices with reset functions have not yet been initialized. Hence, power-on does not guarantee output pin levels, I/O settings or contents of registers. A device is not initialized until the reset signal is received. A reset operation must be executed immediately after power-on for devices with reset functions.

⑤ POWER ON/OFF SEQUENCE

In the case of a device that uses different power supplies for the internal operation and external interface, as a rule, switch on the external power supply after switching on the internal power supply. When switching the power supply off, as a rule, switch off the external power supply and then the internal power supply. Use of the reverse power on/off sequences may result in the application of an overvoltage to the internal elements of the device, causing malfunction and degradation of internal elements due to the passage of an abnormal current.

The correct power on/off sequence must be judged separately for each device and according to related specifications governing the device.

⑥ INPUT OF SIGNAL DURING POWER OFF STATE

Do not input signals or an I/O pull-up power supply while the device is not powered. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Input of signals during the power off state must be judged separately for each device and according to related specifications governing the device.

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"Special": Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support).

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